

REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.15	阿树

Specification

MATERIAL:

Insulator: LCP UL94V-0, BLACK

Contact: C5210

SHELL: SUS304

PLATING:

Contact: G/F OVER Ni

Shell: G/F PLATED ON SOLDER AREANI

PLATED OVERALL

Electrical:

Current Rating :0.5mA AC/DC max.

Voltage Rating :125V AC/DC

Ambient Temperature Range :-20C~+60°C

Storage Temperature Range :-40C~+70°C

Ambient Humidity Range :95% R.H. Max.

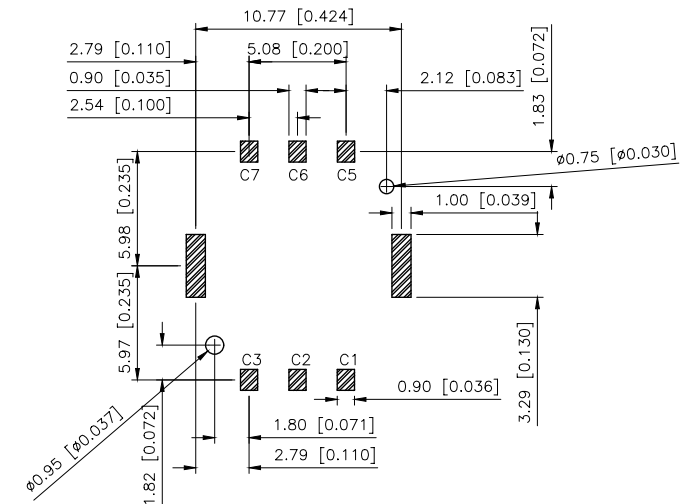
Contact Resistance:100mΩ max.

Insulation Resistance 1000MΩ min./500VDC

Mating Cycles:10,000 Insertions

Reflow peak temp: 260°C +50, 3~5 5

Mating Cycles:3,000 Insertions Min



SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKSIM-304
APPROVED		SIZE: A4	DWG NO.: X-XKSIM-304
			SCALE N/A
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